



Product Change Notification / GBNG-09EEJB041

Date:

16-Aug-2021

Product Category:

Ethernet PHYs

PCN Type:

Manufacturing Change

Notification Subject:

CCB 3473.001 Final Notice: Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 32L VQFN (5x5x0.9mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Affected CPNs:

[GBNG-09EEJB041_Affected_CPN_08162021.pdf](#)

[GBNG-09EEJB041_Affected_CPN_08162021.csv](#)

Notification Text:**PCN Status:**

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of ASE as a new assembly site for selected Micrel KSZ8061 device family available in 32L VQFN (5x5x0.9mm) package using palladium coated copper with gold flash (CuPdAu) bond wire.

Pre and Post Change Summary:

		Pre Change	Post Change
Assembly Site		Taiwan IC Packing Corp (TICP)	ASE Inc. Taiwan (ASE)
Wire material		Cu	CuPdAu
Die attach material		EN4900	EN4900
Molding compound material		G631	G631
Lead frame	Material	C194	C194
	Paddle size	150x150 mils	138x138 mils
	Design	Please see attached Pre and Post Change comparison	

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve on-time delivery performance by qualifying ASE as a new assembly site.

Change Implementation Status:

In Progress

Estimated First Ship Date:

September 19, 2021 (date code: 2139)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Time Table Summary:

Workweek	August 2021					September 2021			
	32	33	34	35	36	37	38	39	40
Qual Report Availability			X						
Final PCN Issue Date			X						
Estimated Implementation Date								X	

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

August 16, 2021: Issued final notification.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_GBNG-09EEJB041_Pre and Post Change_Summary.pdf](#)

[PCN_GBNG-09EEJB041_Qual_Report.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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Affected Catalog Part Numbers (CPN)

KSZ8061MNXI

KSZ8061RNBW

KSZ8061RNDW

KSZ8061RNBW-TR

KSZ8061RNDW-TR

KSZ8061MNXI-TR